

Amendments to the Abstract:

Please amend the abstract as follows:

A leadframe is disclosed comprising a plurality of leads. A method of forming a semiconductor package is provided. The method includes forming a leadframe wherein the conductors or leads of the leadframe extend radially from a first end to a second end such that a portion of each lead has exhibits a generally arcuate shape. The first end is for coupling may be coupled with a printed circuit board. and the The second end is for coupling the may be coupled with a semiconductor die. The generally arcuately-shaped portion of the leads may include a portion which exhibits a constant radius. The generally arcuately-shaped portion may also be formed from a plurality of conductor segments including, for example, at least one generally arcuately-shaped segment. The semiconductor die and at least a portion of the leads may be encapsulated with an insulating material. Alternatively, the leads have a plurality of segments. Each lead has at least three segments disposed between the first end and the second end. The segments forming the leads are disposed such that each lead generally has an arcuate shape. The segments each have substantially the same length, or can have varying lengths. An integrated circuit package is also disclosed including a leadframe having a plurality of leads, at least one semiconductor die coupled with the leads, and an insulating enclosure encapsulating the die and a portion of the leadframe. The leads each extend radially from a first end to a second end such that each lead has a generally arcuate shape. The leads can also have at least three segments disposed between the first end and the second end.